

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	28573	(257/678-733).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 10:31
L6	22	L5 and (stress adj relief adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:32
L7	372	(stress adj relief adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:32
L9	5989	L5 and (stress relief compliant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:17
L10	3137	L9 and (pcb pwb (printed adj circuit) ((circuit wiring) adj board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:40
L11	120	L10 and (compliant adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:59
L12	6492	(361/760-783).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 11:29
L13	39	L12 and (compliant adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:59
L14	155	("4545610" "4617730" "4940181" "5065280" "5142444").PN. OR ("5329423").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 11:14
L15	691	(361/783).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 11:16

L16	26	15 and compliant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:16
L17	165	15 and (stress relief)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:20
L18	712	(257/669).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 11:21
L19	1197	12 and frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:35
L20	1845	(174/260).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 11:35
L21	491	20 and (stress)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:35
L22	0	20 and (relief adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:37
L23	31	20 and (stress adj relief)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:37

L24	107	("20010045644" "20020053731" "20020072214" "20020079562" "20020079572" "20020096767" "20020098617" "20020109226" "20020135065" "20020171144" "20020180040" "20030111726" "20030138613" "3790866" "4611238" "5045921" "5065281" "5173766" "5208504" "5216278" "5285352" "5291062" "5294826" "5366589" "5394009" "5397917" "5397921" "5409865" "5433631" "5438216" "5474957" "5490324" "5534467" "5541450" "5552635" "5572405" "5578869" "5583377" "5583378" "5642261" "5648679" "5650659" "5691567" "5717252" "5736785" "5796170" "5798909" "5801432" "5835355" "5843808" "5844168" "5866949" "5883430" "5889324" "5894410" "5901041" "5903052" "5905633" "5907903" "5920117" "5949137" "5953589" "5972734" "5977626" "5986340" "5986885" "5998241" "5999415" "6002147" "6002169" "6011304" "6011694" "6020637" "6028358" "6057601" "6060777" "6069407" "6077724" "6084297" "6084777" "6114761" "6117797" "6122171" "6133064" "6140707" "6160705" "6162659" "6163458" "6166434" "6184580" "6201300" "6212070" "6242279" "6246111" "6288444" "6347037" "6362525" "6369455" "6380623" "6472741" "6525942" "6541832" "6545351" "6552266" "6552428" "6563712" "6583516"). PN. OR ("6861750").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 11:43
L25	1845	(174/260).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 11:44
L26	456	(174/252).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 11:44
L27	58	25 and 26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:47

L28	1442	361/807	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 11:47
L29	107	("20010045644" "20020053731" "20020072214" "20020079562" "20020079572" "20020096767" "20020098617" "20020109226" "20020135065" "20020171144" "20020180040" "20030111726" "20030138613" "3790866" "4611238" "5045921" "5065281" "5173766" "5208504" "5216278" "5285352" "5291062" "5294826" "5366589" "5394009" "5397917" "5397921" "5409865" "5433631" "5438216" "5474957" "5490324" "5534467" "5541450" "5552635" "5572405" "5578869" "5583377" "5583378" "5642261" "5648679" "5650659" "5691567" "5717252" "5736785" "5796170" "5798909" "5801432" "5835355" "5843808" "5844168" "5866949" "5883430" "5889324" "5894410" "5901041" "5903052" "5905633" "5907903" "5920117" "5949137" "5953589" "5972734" "5977626" "5986340" "5986885" "5998241" "5999415" "6002147" "6002169" "6011304" "6011694" "6020637" "6028358" "6057601" "6060777" "6069407" "6077724" "6084297" "6084777" "6114761" "6117797" "6122171" "6133064" "6140707" "6160705" "6162659" "6163458" "6166434" "6184580" "6201300" "6212070" "6242279" "6246111" "6288444" "6347037" "6362525" "6369455" "6380623" "6472741" "6525942" "6541832" "6545351" "6552266" "6552428" "6563712" "6583516"). PN. OR ("6861750").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:04
L30	17	("5307237" "5490324" "5640047" "5642261" "5710459" "5741729" "5825628" "5894410" "5990550" "6282094" "6359341" "6448639"). PN. OR ("6525942").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:04
L31	19	("5285352" "5583377" "5642261" "5741729" "5825628" "5942795" "5959356" "6008536" "6023098" "6034427" "6038137" "6117705" "6125042").PN. OR ("6282094").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:07

L32	51	("4835598" "4893172" "4954878" "5103290" "5159434" "5182628" "5216278" "5433822" "5455456" "5468999" "5583747" "5598036" "5598321").PN. OR ("5959356").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:08
L33	56	("3399332" "4737395" "4829403" "4835598" "4890152" "5045921" "5233225").PN. OR ("5583377").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:09
L34	76	("4807021" "4918514" "5214308" "5216278" "5220200" "5233504" "5250848" "5334857").PN. OR ("5598036").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:11
L35	2	("5598036").PN. OR ("6657124").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:13
L36	11	("5477933" "5598036" "5641946" "5662725" "5716222" "5724728" "5751556" "5760469" "5985695" "6014318").PN. OR ("6239383").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/17 12:55
L37	416	(solder adj ball adj diameter)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 12:56
L38	217	37 and BGA	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:01
L39	5716	ic with microprocessor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:02
L40	109	39 and bga and thermal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 15:31
L41	8	(simultaneous same (screen adj (printed printing))) and bga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:36
L42	24	(simultaneous same (screen adj (printed printing))) and tab	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:38

L43	1316	(simultaneous adj (forming processing)) (screen adj (printed printing))) and bga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:39
L44	5	(simultaneous adj (forming processing)) and (screen adj (printed printing)) and bga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:48
L45	1	(simultaneous adj (forming processing)) and (screen adj (printed printing)) and tab	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:49
L46	39	(substrate with multiple with (forming processing)) and (screen adj (printed printing)) and bga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 14:02
L47	21	(substrate with multiple with (forming processing)) and (screen adj (printed printing)) and tab	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 13:56
L48	276	(substrate with multiple with (forming processing)) and (screen adj (printed printing))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 14:02
L49	1896	(438/110-114).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 14:02
L50	76	49 and (screen adj (printed printing)) and bga	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 14:22
L51	2149	(thermally adj conductive) same resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 14:22
L52	224	(thermally adj conductive) adj resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 14:22

L53	2	("6219241").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 16:04
S1	1845	(174/260).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 10:20
S2	28573	(257/678-733).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/17 10:20
S3	5989	S2 and (stress relief compliant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:21
S4	3137	S3 and (pcb pwb (printed adj circuit) ((circuit wiring) adj board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:24
S5	1516	S4 and @py>"2001"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:22
S6	10	S4 and (stress adj relief adj layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/17 10:40